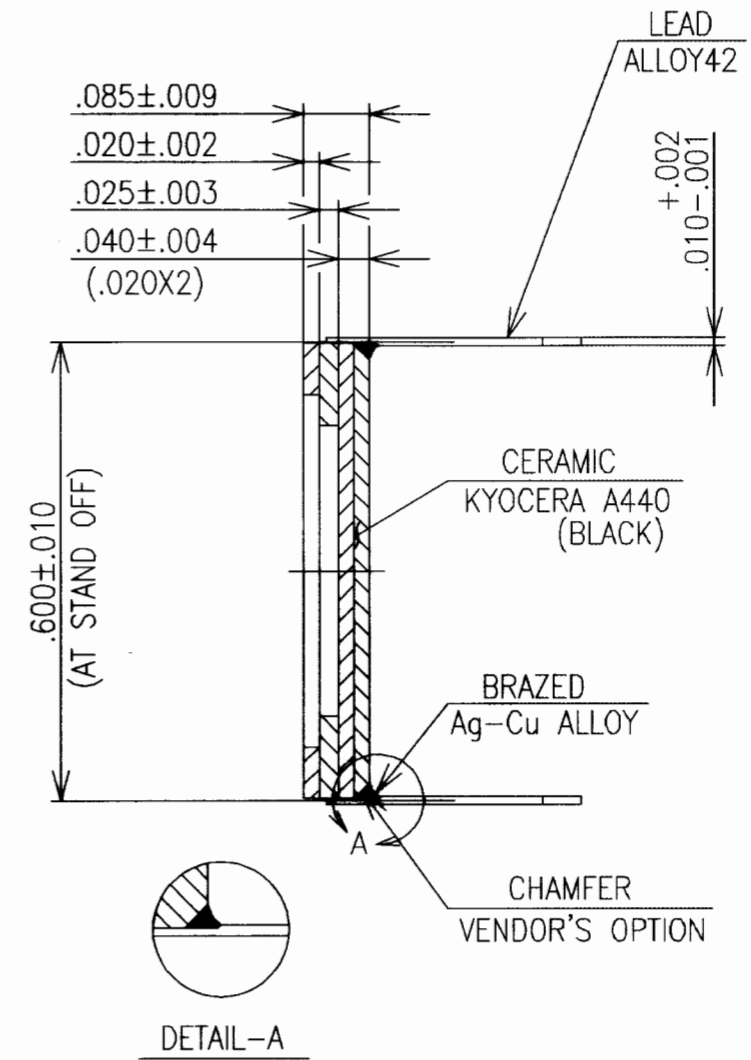
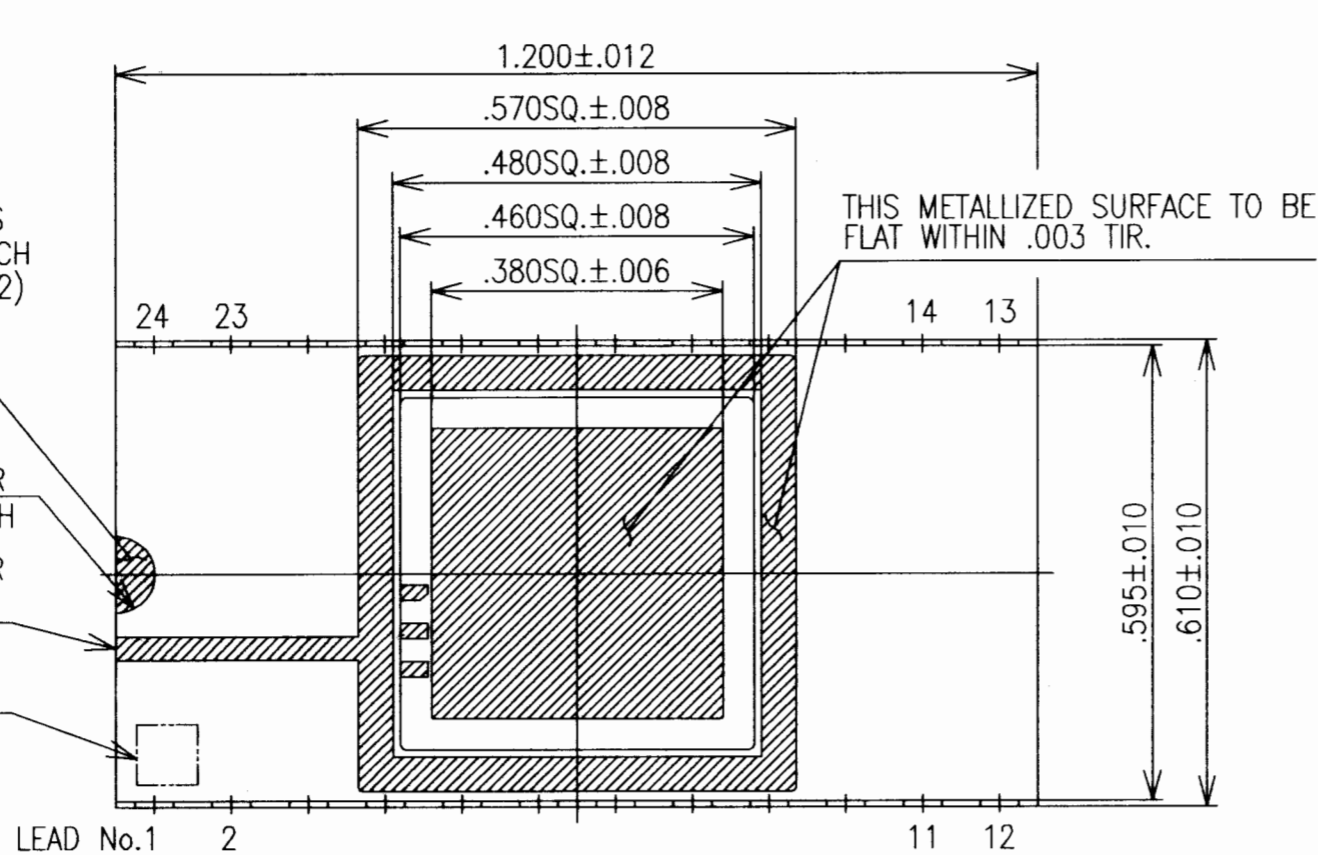
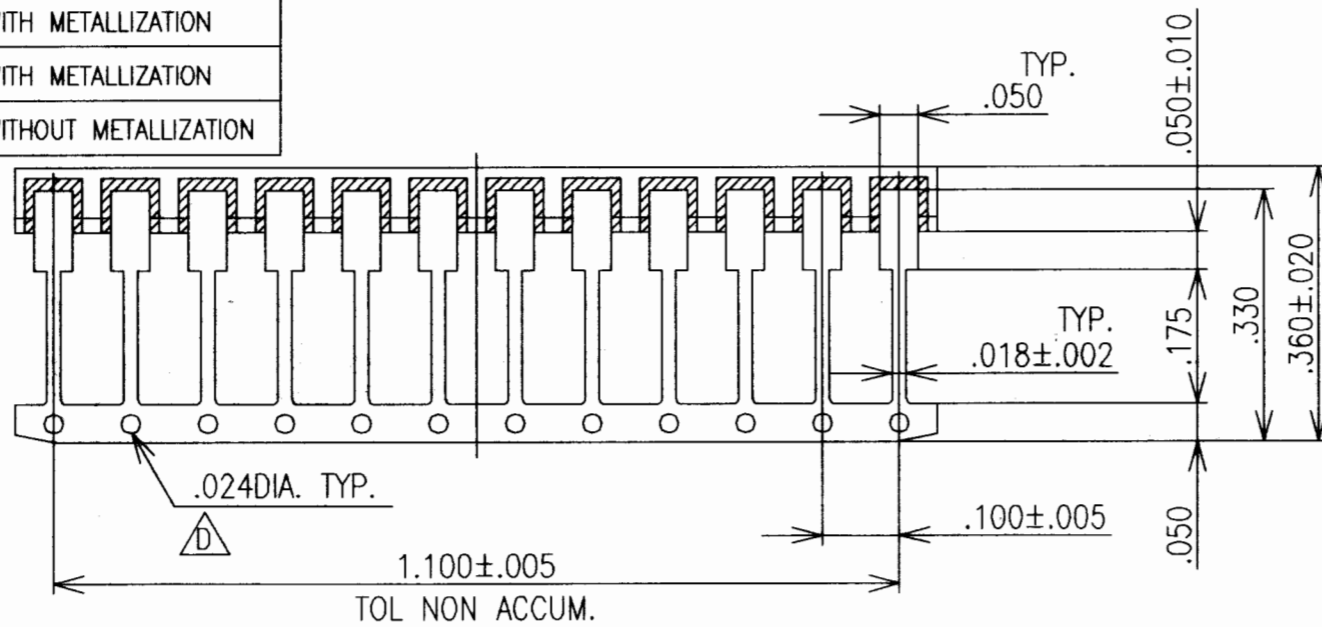


THIS METALLIZED AREA IS CONNECTED TO DIE ATTACH PAD.(ONLY PART No.01,02)

.050R NOTCH
GRIND AFTER Au PLATING
INDEX MARK SEE TABLE



PART No.	INDEX MARK	LEAD TIED DOWN	NOTCH AREA METALLIZED
01	□	NIL	WITH METALLIZATION
02	▽	LEAD No.1 ONLY	WITH METALLIZATION
03	□	NIL	WITHOUT METALLIZATION



NOTES

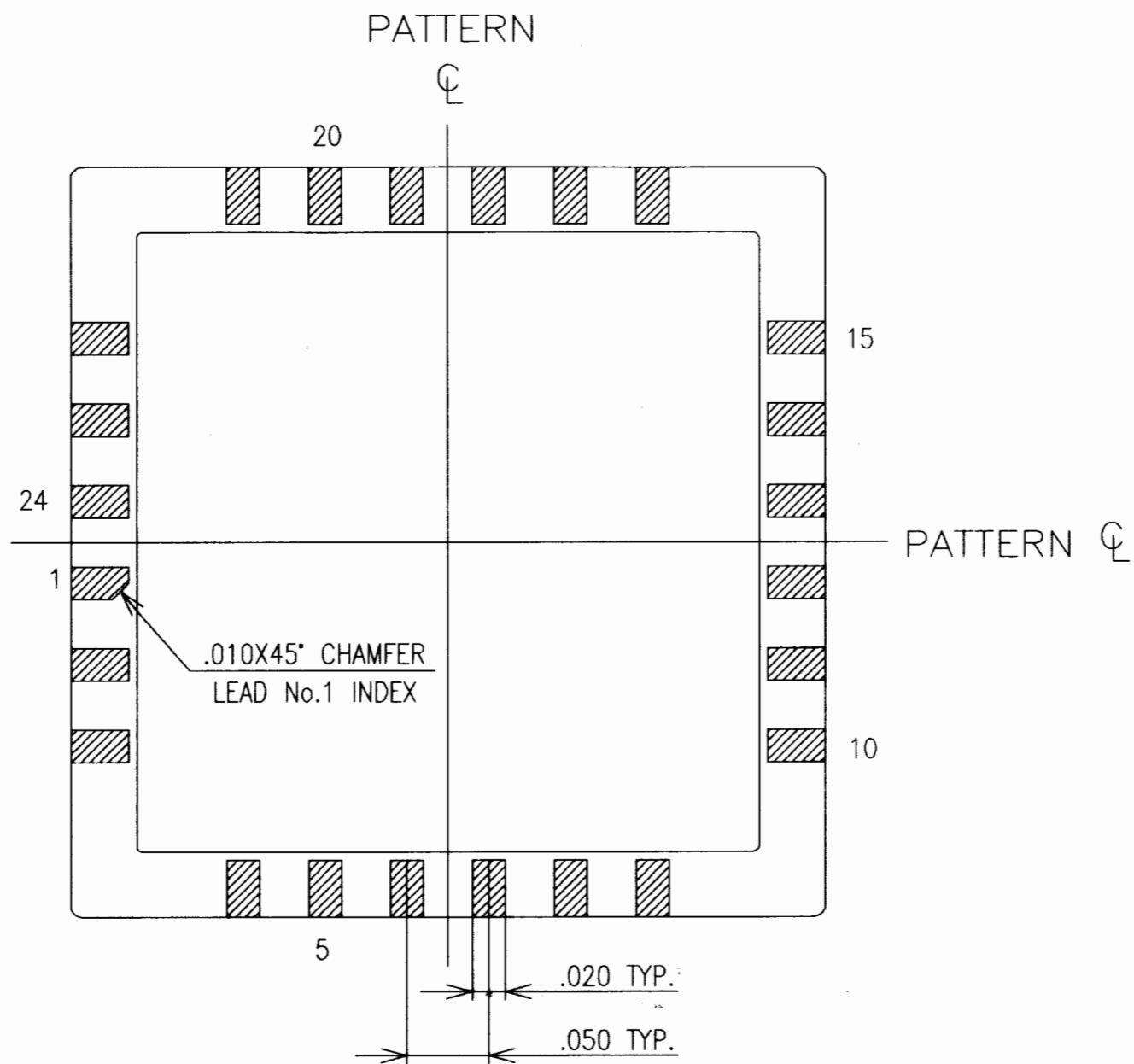
1. PLATING THICKNESS TO BE PER CUSTOMER'S SPECIFICATION.
2. SEAL AREA TO BE METALLIZED.
3. DIE ATTACH AREA TO BE METALLIZED.
4. LEAD RESISTANCE : 0.30 OHM MAX.
5. WIRE BOND PAD CONNECTED TO CORRESPONDED OUTER LEADS.
6. MISALIGNMENT OF METALLIZATION PATTERN IN CAVITY SHALL BE ACCEPTED DUE TO LAYER MISALIGNMENT.

SB0241516-3	S=0 D=0
SB0241516-2	S=0 D=1
SB0241516-1	S=0 D=0

MODIFICATION						NAME	TOLERANCE	DRAWN	CHECKED	APPROVED	DATE
						24 LEAD SIDE BRAZED PACKAGE	UNLESS OTHERWISE SPECIFIED	S.S	K.M	T.A	DEC.04.'78
△	ADDED : PART No.3 , NOTE 5,6 , DELETED : VENDOR'S OPTION					SCALE 4 / 1	±.005 THIRD ANGLE PROJECTION	Y. Na	T.A	S.A	DRAWING NO. KD-78516-D
△	REDRAWN (CONVERTED CAD DATA)					MATERIAL AS INDICATED					
	CHANGED					DATE					



KYOCERA CORPORATION
KYOTO JAPAN



BONDING PATTERN

MODIFICATION						NAME	TOLERANCE	DRAWN	CHECKED	APPROVED	DATE
						24 LEAD SIDE BRAZED PACKAGE	UNLESS OTHERWISE SPECIFIED	M.K	S.T/S.F	T.A	APR.07.'93
						SCALE 10 / 1					
						MATERIAL	THIRD ANGLE PROJECTION				
△	REDRAWN (CONVERTED CAD DATA)	AUG.21.'93	S.SH	H.S/S.F	T.A		KYOCERA CORPORATION KYOTO JAPAN	DRAWING NO.			SHEET
	CHANGED	DATE	DRAWN	CHECKED	APPROVED			KD-78516-D			2 / 2